

Description

Yantel's surface mount catalog bandpass filters utilize Yantel's low loss temperature stable materials which offer small size and minimal performance variation over temperature. The catalog BPF's are offered in a variety of frequency bands, which offers a drop in solution with highly repeatable performance.

Features

- Small Size
- Fully Shielded Component
- Solder Surface Mount Package
- Moisture Sensitivity Level: MSL1
- Frequency Stable over Temperature
- Operating & Storage Temp: -55°C to +125°C
- Characteristic Impedance: 50Ω

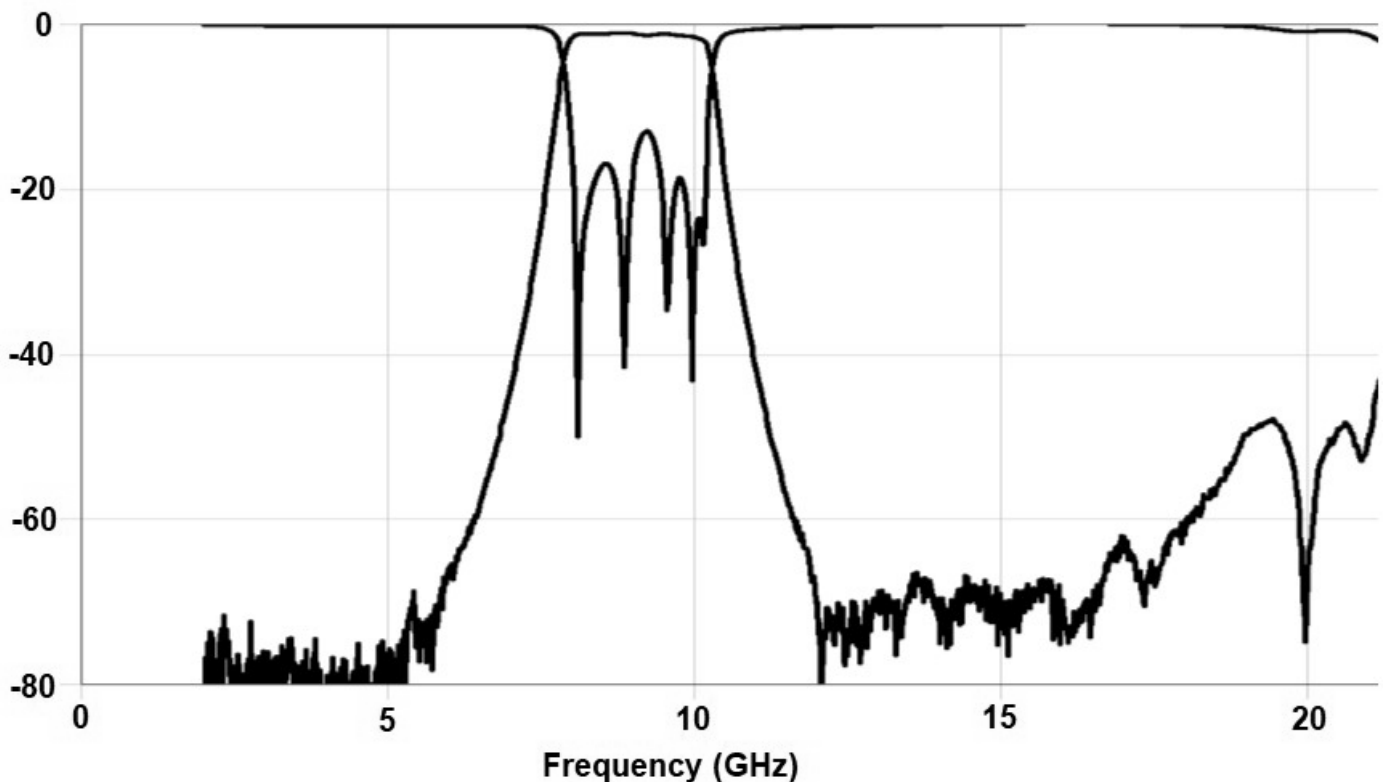
Specifications*

Parameter	Frequency Range (GHz)	Min	Typ.	Max
Insertion Loss (dB)	8.1 - 10.1		2.5	2.75
Return Loss (dB)		10.0	12.0	
Low Side Rejection (dB)	DC - 6.8	40.0	50.0	
High Side Rejection (dB)	11.25 - 20.0	40.0	45.0	
CW Input Power** (W)				10
$\theta_{jc} \left(\frac{^{\circ}C}{W} \right)$	7.5			
Size (L x W x H)	0.400 x 0.150 x 0.103 in 10.6 x 3.81 x 2.61 mm			

*Electrical specifications based on typical probed performance at room temperature. Insertion loss shall vary ± 0.5 dB over temperature.

**Power rating assumes the component will be mounted to a PCB with good thermally conducting ground vias as outlined in the recommended PCB layout that are connected to an adequate heat sink. Max power is based on 125°C base temperature.

Typical Measured Performance



*Typical de-embedded measured performance mounted on a connectorized test fixture. DEB is 0.254mm RO4350B with 50.00hm CPW ground traces going into the ports at room temperature.

Yantel Corporation

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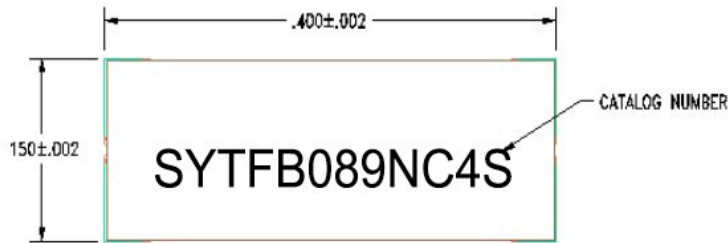
Tel: 86-755-8355-1886 Fax: 86-755-8355-2533

For detailed performance specs & shopping online see Yantel web site : www.yantel-corp.com

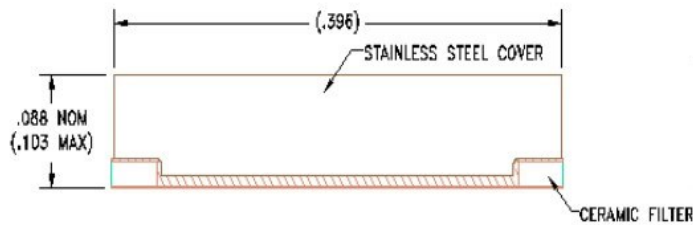
Physical Dimensions

Units = inches

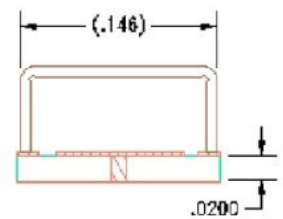
Top View



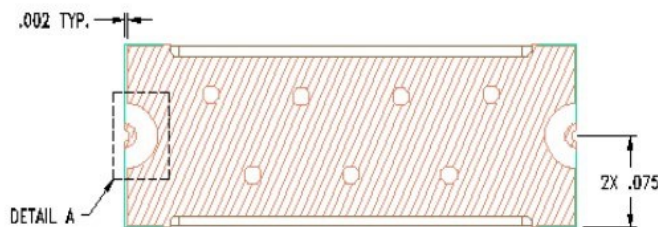
Side View



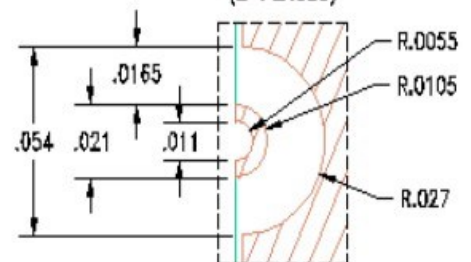
End View



Bottom View



DETAIL A (2 PLACES)



Notes :

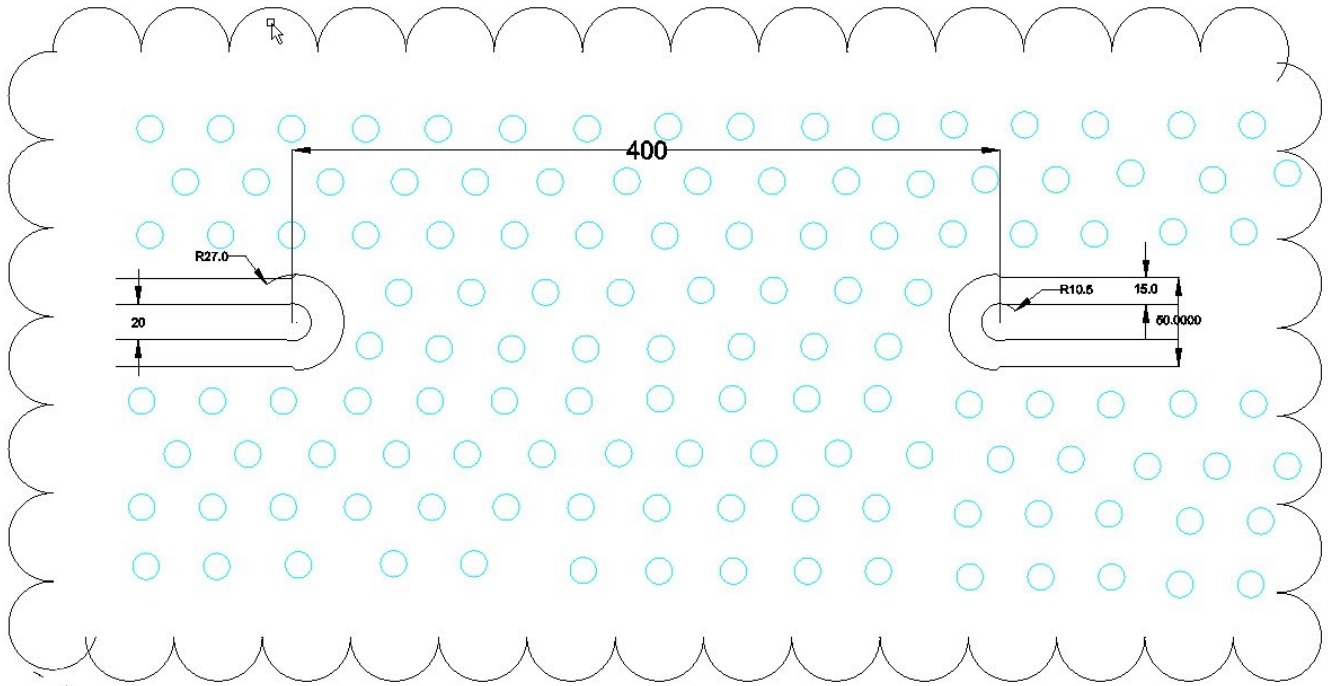
- Termination Finish:
ENIG: 3 - 6 μ inch Au over 50 μ inch Ni
- Maximum Assembly Process Temperature: 250°C

Tolerances:

For values with 3 decimal places ± 0.001

For values with 4 decimal places ± 0.0005

Recommended PCB Layout



Unit =mils

Note:

- 50 Ω trace dimensions are application specific.
- Ensure adequate grounding beneath the part.